



High heat resistance
Low warpage,
Low stress
High insulation

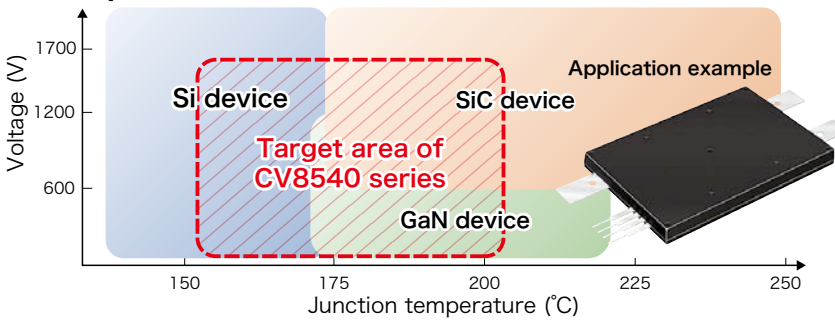
Applications
IC Package/Automotive
 Power devices used in industry/
 Automotive inverters

CV8540 series

For high heat resistance power devices semiconductor encapsulation materials

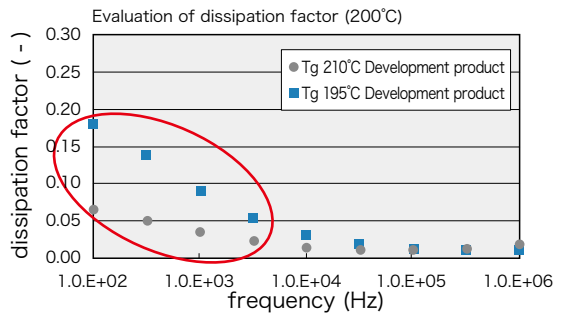
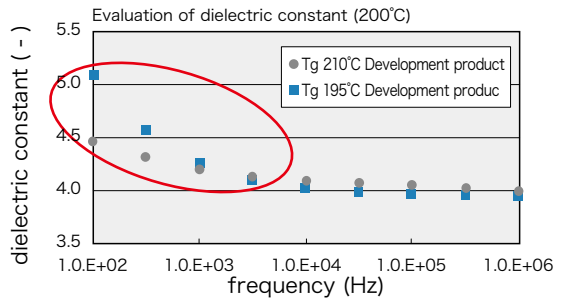
By adopting a new epoxy system, this material has excellent heat resistance and can be applied to the next generation power devices (SiC, GaN).
 Contribute to improving power module performance and reliability under high temperature environment.

Concept



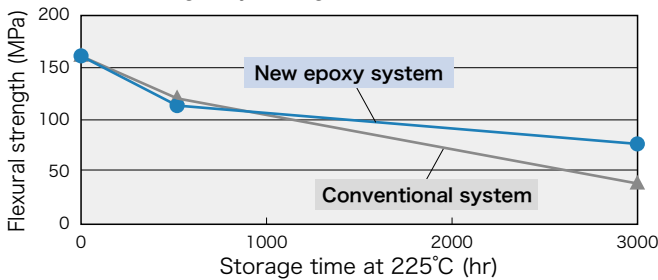
Dielectric property (Tg dependence)

Effective for high-temperature low dielectric constant and low dissipation factor.



High heat resistance

Change in flexural strength by storage time at 225°C.



General properties

Item	Unit	LEXCM _{CF} CV8540 series
Tg (TMA)	°C	185-205
CTE 1	ppm/°C	11-13
CTE 2		48
Flexural strength (25°C)	MPa	130-160
Flexural modulus (25°C)	GPa	15-19
Flammability (UL-94)	-	V-0
Mold shrinkage	%	0.25-0.4
Gelation time	sec	30-40

Please see our website for Notes before you use.

The above data are typical values and not guaranteed values.

industrial.panasonic.com/ww/electronic-materials

Panasonic Industry CV8540